

Supporting Information

Impact of molecular planarity on electronic devices in thienoisindigo-based organic semiconductors

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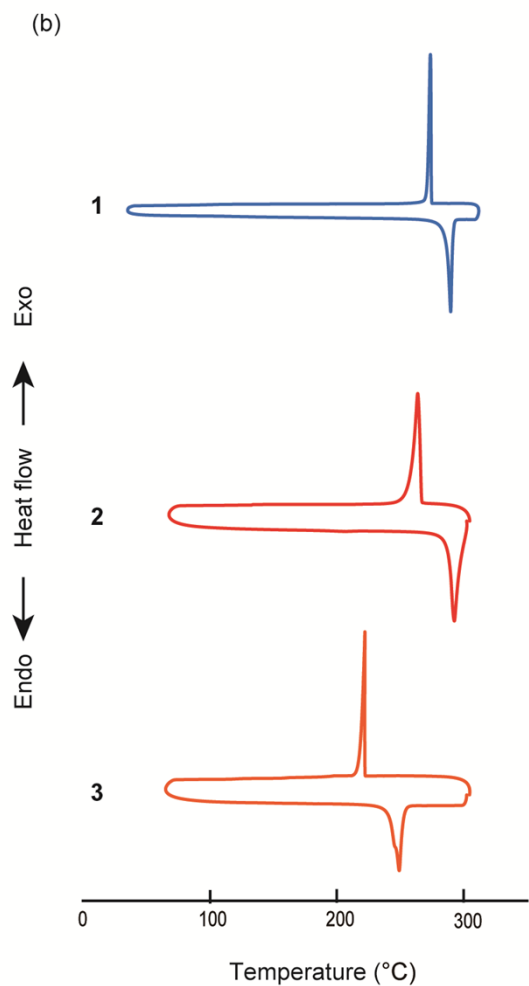
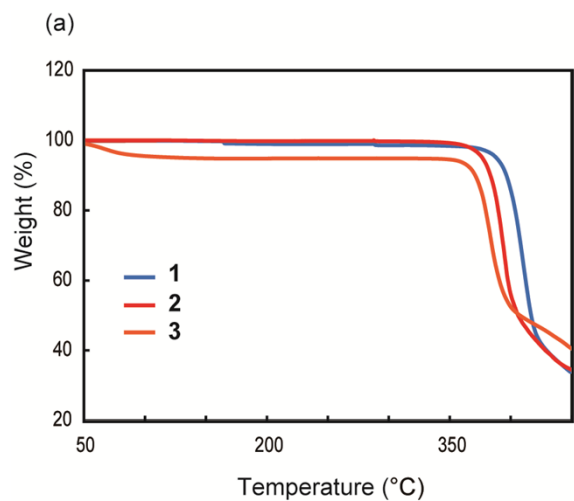


Fig. S1 (a) TGA curves of **1-3** at the heating rate of 10 °C / min under a nitrogen atmosphere. (b) DSC curves of **1-3** at the scan rate of 5 °C / min under a nitrogen atmosphere.

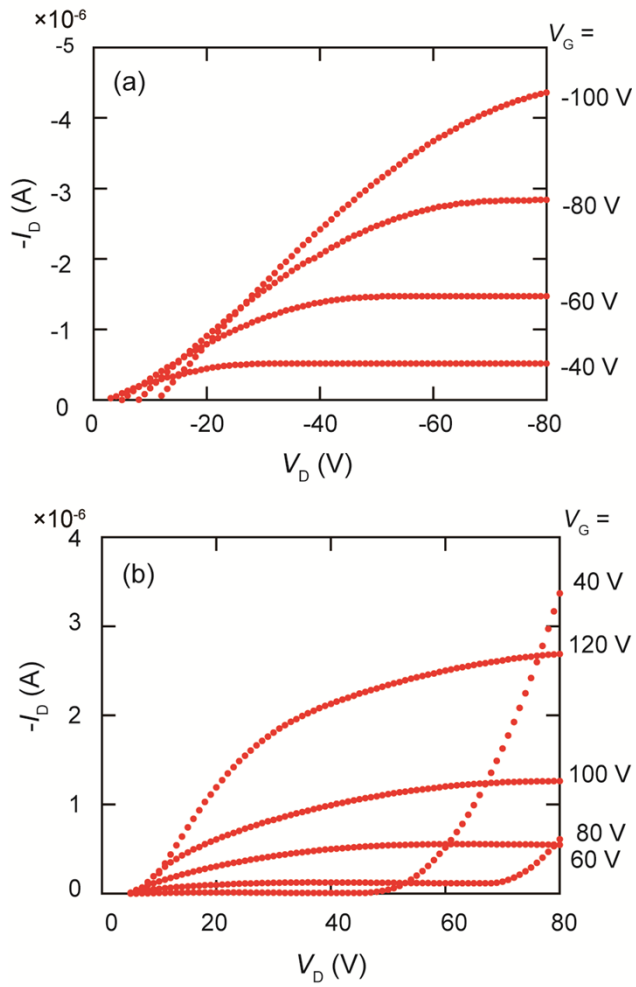


Fig. S2 (a) p-channel and (b) n-channel output characteristics of a top contact device of **1** prepared on a TTC modified substrate.

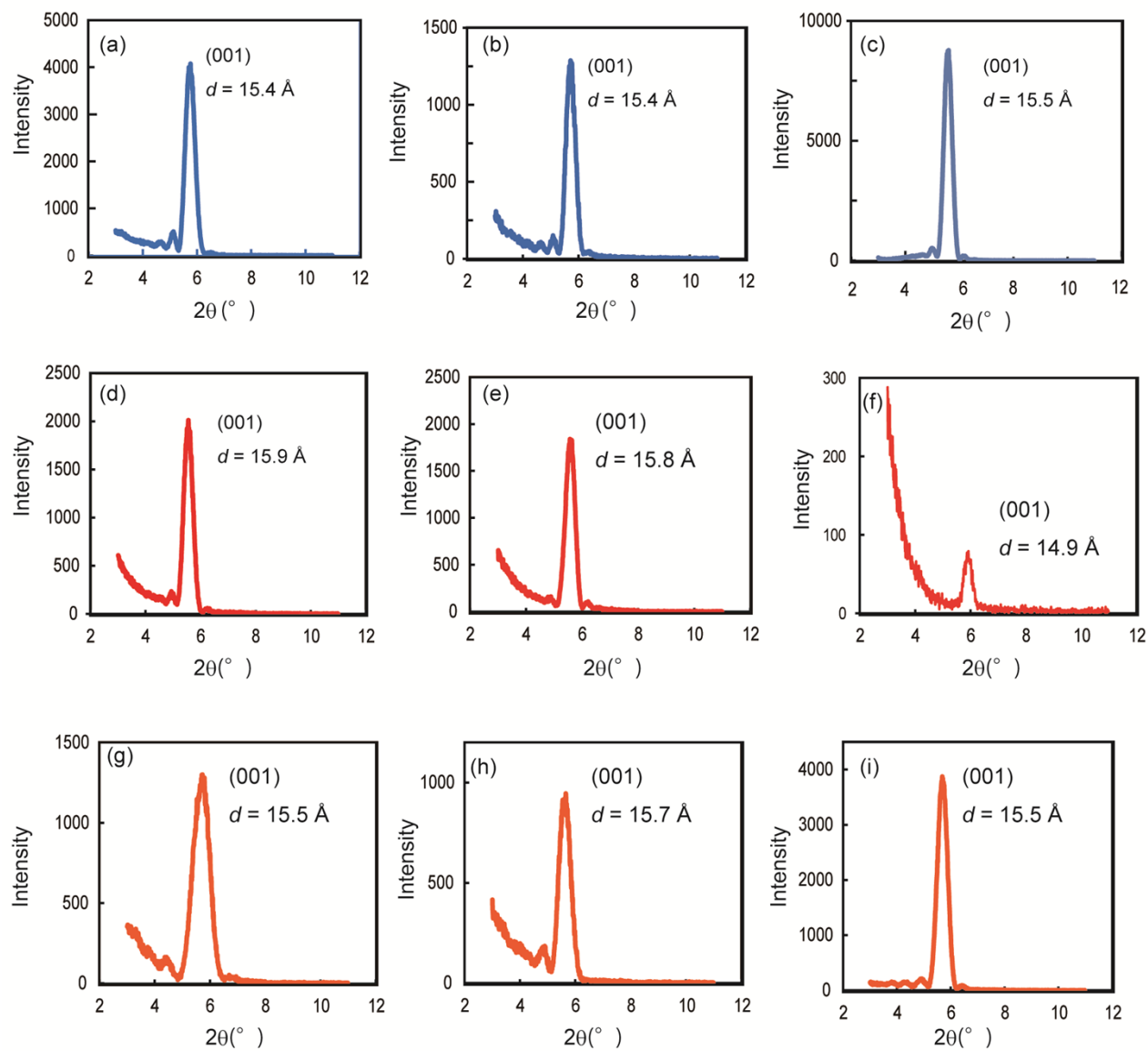


Fig. S3 XRD patterns of **1** thermally evaporated films on (a) bare, (b) HMDS, and (c) OTMS substrates. XRD patterns of **2** on (d) bare, (e) HMDS, and (f) OTMS substrates. XRD patterns of **3** on (g) bare, (h) HMDS, and (i) OTMS substrates.

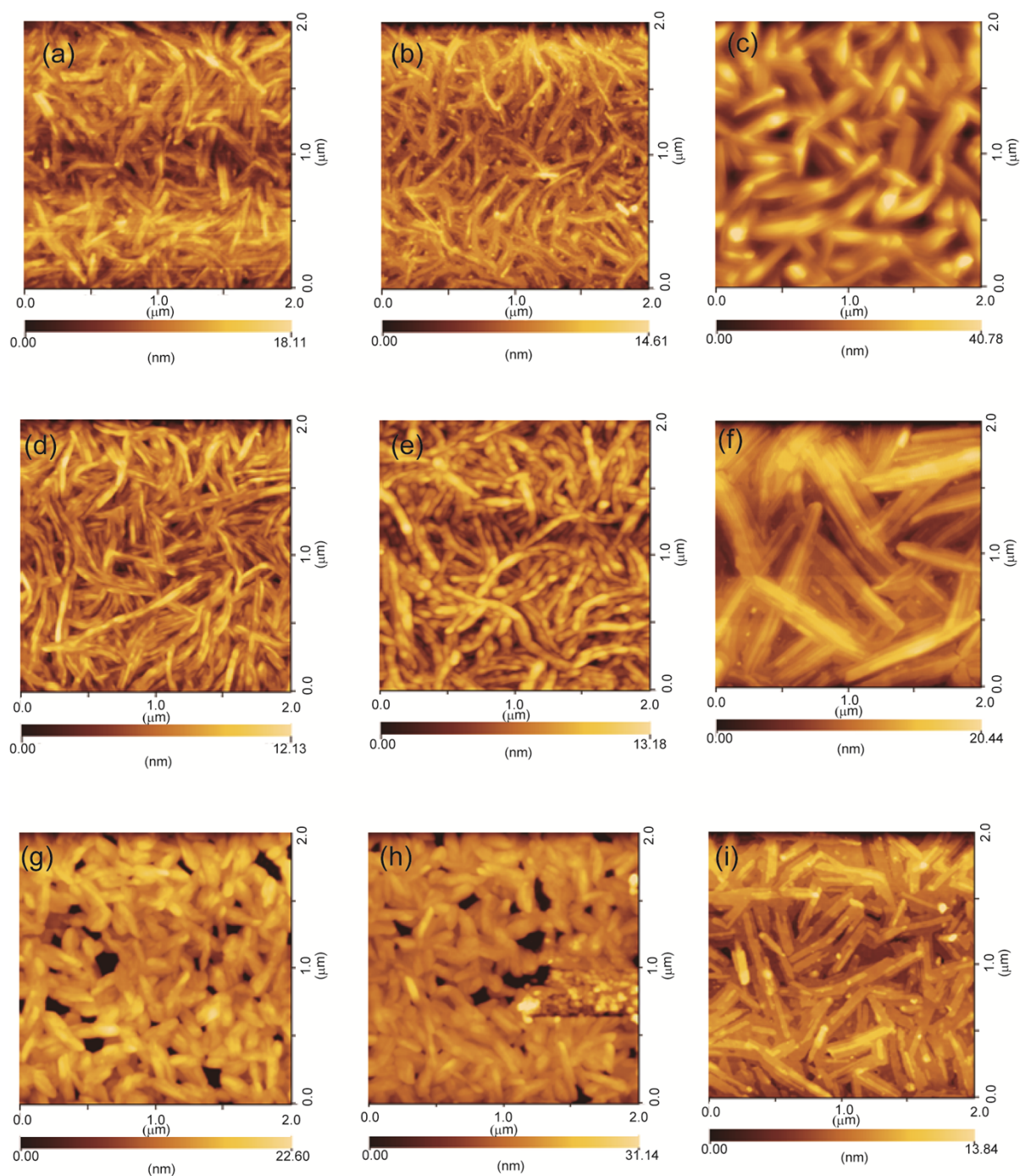


Fig. S4 AFM images of **1** thermally evaporated on (a) bare, (b) HMDS, and (c) OTMS substrates.

AFM images of **2** on (d) bare, (e), HMDS, and (f) OTMS substrates. AFM images of **3** on (g) bare, (h)

HMDS, and (i) OTMS substrates.

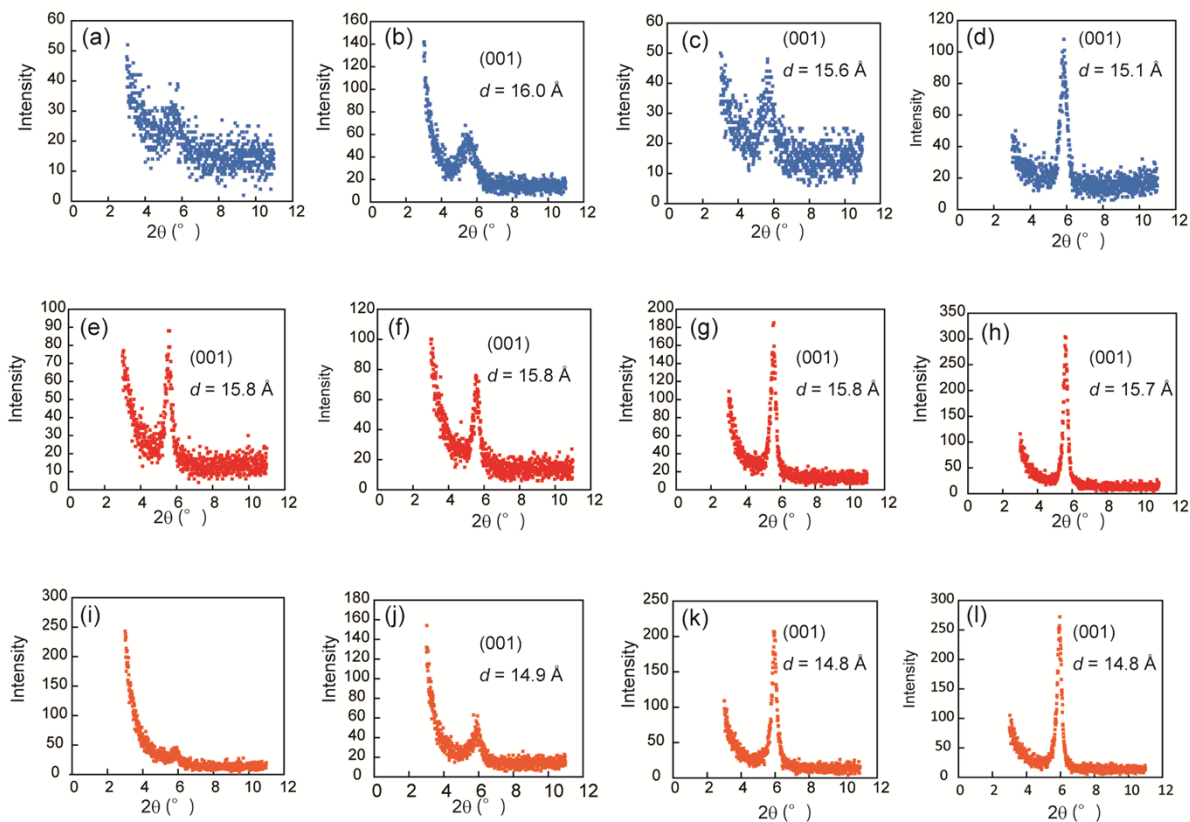


Fig. S5 XRD patterns of blended films of **1** (a) as cast, and after annealing at (b) 80 °C, (c) 110 °C, and (d) 150 °C. XRD patterns of blended films of **2** (e) as cast, and after annealing at (f) 80 °C, (g) 110 °C, and (h) 150 °C. XRD patterns of blended films of **3** (i) as cast, and after annealing at (j) 80 °C, (k) 110 °C, and (l) 150 °C.